

Subst. Form PTO-1449  APPLICANT'S INFORMATION DISCLOSURE STATEMENT	Atty. Docket No.: END920030018US1 (IEN-10-5765)	Serial No.: <del>To be assigned</del>  10/666 775
	Applicant: Biggs et al	
	Filing Date: Herewith 9/18/03	Group: 2813

## U.S. PATENT DOCUMENTS

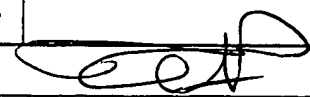
Initial*		Document No.	Date	Name	Class	Subcl.	Filing Date
TSP	AA	5,885,891	03/23/99	Miyata et al	438	612	07/16/97
TSP	AB	6,077,766	06/20/00	Sebesta et al	438	618	06/25/99
TSP	AC	6,376,371 B1	04/23/02	Jain et al	438	681	05/12/00
TSP	AD	6,387,793 B1	05/14/02	Yap et al	438	612	03/09/00
	AE						
	AF						
	AG						
	AH						
	AI						
	AJ						
	AK						

## FOREIGN PATENT DOCUMENTS

		Document No.	Date	Country	Class	Subcl.	Translation?
<del>/</del>	AL		<del>/</del>	<del>/</del>			<del>/</del>
<del>/</del>	AM		<del>/</del>	<del>/</del>			<del>/</del>
<del>/</del>	AN		<del>/</del>	<del>/</del>			<del>/</del>

## OTHER DOCUMENTS

TSP	AO	IBM Technical Disclosure Bulletin, "Electroless Gold Plating of Thick Films", M. M. Haddad, Vol. 16, No. 4, September, 1973
	AP	
	AQ	
	AR	
	AS	
	AT	

Examiner: 

Date Considered:

10/19/04

\*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; draw line through citation if in conformance and not considered. Include copy of this form with next communication to applicant.